

Applicable standard						
Rating	Operating temperature range	-40°C to +85°C(Note 1)	Storage temperature range		-10°C to +60°C(Note 2)	
	Operating humidity range	40% to +80%	Storage humidity range		40% to +70%(Note 2)	
	Voltage	250V AC	UL・CSA	Voltage	AC 30V	
	Current	2A	Rating	Current	2A	
Specifications						
Item		Test method		Requirements		QT    AT
Construction						
General examination		Visually and by measuring instrument.		According to drawing.		X    X
Marking		Confirmed visually.				X    X
Electric characteristics						
Contact resistance		100mA (DC or 1000 Hz).		30mΩ MAX.		X    —
Insulation resistance		500V DC.		1000MΩ MIN.		X    —
Voltage proof		650V AC for 1 min.		No flashover or breakdown.		X    —
Mechanical characteristics						
Mechanical operation		30 times insertions and extractions.		① Contact resistance: 30mΩ max. ② No damage, crack or looseness of parts.		X    —
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.		① No electrical discontinuity of 1μs. ② No damage, crack or looseness of parts.		X    —
Shock		490 m/s <sup>2</sup> duration of pulse 11 ms at 3 times for 3 directions.		① No electrical discontinuity of 1μs. ② No damage, crack or looseness of parts.		X    —
Environmental characteristics						
Rapid change of temperature		Temperature -55→ 5 to 35→+85→ 5 to 35 °C Time 30→ 2 to 3 → 30→ 2 to 3 min Under 5 cycles.		① Contact resistance: 30mΩ MAX. ② Insulation resistance: 1000MΩ MIN. ③ No damage, crack or looseness of parts.		X    —
Damp heat (Steady state)		Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.		① Contact resistance: 30mΩ MAX. ② Insulation resistance: 500MΩ MIN. ③ No damage, crack or looseness of parts.		X    —
Resistance to soldering heat		①Automatic soldering(frow) Solder temperature, 260 °C for Immersion,duration, 10 sec. ②Manual soldering Soldering iron temperature : 300 °C Soldering time: 2 sec. No strength on contact.		No deformation of case of excessive looseness of the terminals.		X    —
Solderability		Soldered at solder temperature, 230°C for insertion duration, 3sec.		Solder shall cover a minimum of 95 % of the surface being immersed.		X    —
Remarks						
Note 1:Including the temperature rise by current.						
Note 2:Apply to the condition of long term storage for unused products before pcb on board, after pcb board,operating temperature and humidity range is applied for interim storage during transportation.						
Note 3:Non-condensing.						
	Count	Description of revisions	Designed		Checked	Date
△	0					
Unless otherwise specified , refer to IEC 60512.				Approved	KI. AKIYAMA	15. 07. 28
				Checked	TS. FUKUSHIMA	15. 07. 27
				Designed	MI. SAKIMURA	15. 07. 27
				Drawn	MI. SAKIMURA	15. 07. 27
Note    QT:Qualification Test    AT:Assurance Test X:Applicable Test			Drawing no.		ELC-020818-24-00	
<b>HRS</b>	Specification sheet		Part no.		DF11-10DP-2DSA (24)	
	Hirose electric co., ltd.		Code no.		CL543-0520-0-24	△ 1/1